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EMPA Materials Science & Technology

IEEE-CPMT Switzerland Chapter &
Swiss Federal Laboratories for Materials Science and Technology (EMPA)

Seminar on
Reliability of Electronic Components & Systems

EMPA Dübendorf, 24th June 2013

Dear IEEE CPMT members,

The CPMT Switzerland Chapter in cooperation with the Swiss Federal Laboratories for Materials Science and Technology (EMPA) organizes a half-day seminar covering various topics within the field of reliability of electronic components and systems. The goal of this seminar is to provide a platform where people can exchange their activities, interests and solutions.

Seminar Program

14:20 – 14:40 Welcome and introduction

- Welcome address (Hamit Duran, IEEE CMPT chapter chair)
- Introduction to EMPA (Günter Grossmann, EMPA)

14:40 – 15:55 Technical presentations – Part 1

- Reliability of large area solder joints: Numerical modeling and experimental results (Dr. Gernot Riedel, ABB)
- Solder bump process optimization (Dr. René Zingg, Melexis)
- Reliability of the cohesiveness of diverse connection technologies (Jagoda Karlsson, Microdul)

15:55 – 16:10 Short break / coffee

16:10 – 17:00 Technical presentations – Part 2

- Design of accelerated tests for solder joints (Günter Grossmann, EMPA)
- Denser scalable IC packages require jumps in technology and reliability (Gerd Schlottig, IBM)

17:00 – 18:00 Lab tour EMPA

18:00 – 19:00 Apéro / Networking

Location: EMPA Akademie, Überlandstrasse 129, 8600 Dübendorf, Switzerland (see attached instructions)
Date: 24. June 2013
Time: 14:20 – 19:00 (incl. EMPA lab visit)
Local contact: Günter Grossmann (guenter.grossmann@empa.ch, +41 58 765 42 79)
Web: www.ieee.ch/chapters/cpmt, www.empa.ch

Please register by E-mail (hamit.duran@ch.abb.com) before 17th June 2013